



Tin-Lead Solder Paste

SH63-LXA

Rev. 2019/01/09 Ver. 01-01

BASIC OVERVIEW



Sn63Pb37 Solder Paste
No Clean
Halide-Free

APPLICATIONS

The Solder Paste is Intended for Industrial Use Only
Universal Tin-Lead SMD Solder Paste
Wide Range of Applications and PCB designs

SPECIFICATION

Appearance	Gray paste w/o visible foreign and clusters		
Alloy Composition	Sn63/Pb37		JIS-Z-3282
Melting Point	183°C		
Particle Size	(Type 3)	20µm - 45µm	J-STD-005
	(Type 4)	20µm - 38µm	
Powder Shape	Spherical		
Flux Content	10.0 ± 1.0 wt%		JIS-Z-3197
Viscosity	200 ± 30 Pa.s (25±1°C, 10rpm, Malcom)		JIS-Z-3284
Flux Type	ROLO		J-STD-004

ALLOY COMPOSITION

(Sn)	(Pb)	(Ag)	(Cu)	(Ni)	(Sb)	(Bi)	(Cd)	(Au)	(In)	(Al)	(As)	(Fe)	(Zn)
63.0 ± 0.5	REM.	0.10 MAX	0.05 MAX	0.01 MAX	0.05 MAX	0.10 MAX	0.002 MAX	0.05 MAX	0.10 MAX	0.001 MAX	0.03 MAX	0.02 MAX	0.001 MAX

(wt%)



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PERFORMANCE & RELIABILITY

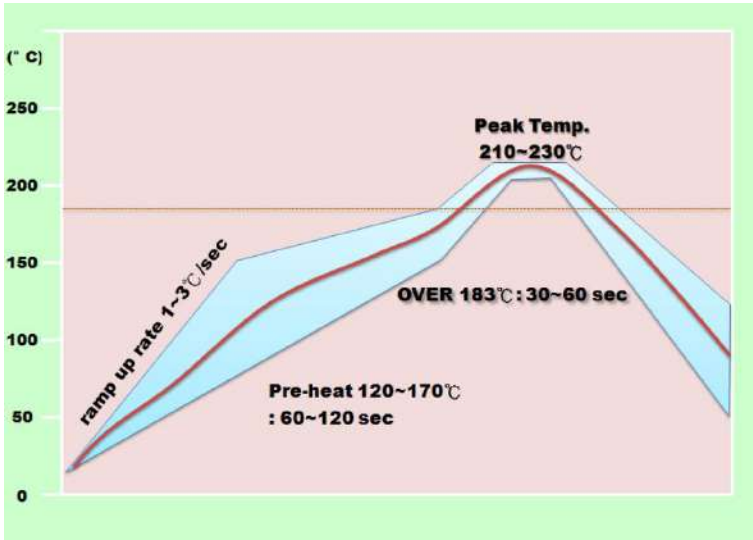
Copper Plate Corrosion Test	Pass	IPC-TM-650, 2.6.15
Halide Content Test	ROLO	IPC-TM-650, 2.3.28.1
Copper Mirror Test	Pass	IPC-TM-650, 2.3.32
Viscosity Test (25°C,10 rpm)	200±30 Pa.s	JIS-Z-3284
Spreading Test	> 90%	JIS-Z-3197
Tackiness Test (gf)	> 120 (8hrs)	JIS-Z-3284
Slump Test	Pass	JIS-Z-3284
Solder Ball Test	Pass	JIS-Z-3284

S.I.R. Test ▲	Pass	IPC-TM-650, 2.6.3.7
Electro Migration Test ◆	Pass	IPC-TM-650, 2.6.14.1

▲ Test Conditions: 40°C, 90% RH for 168hrs

◆ Test Conditions: 65°C, 88.5% RH for 596 hrs

RECOMMENDED REFLOW PROFILE



- Ramp Up Rate (30-120°C): 1.0-3.0°C/s
- Pre-heating Time (120-170°C): 60-120s
- Time Period Above 183°C: 30-60s
- Peak Temperature: 210-230°C
- Ramp Down Cooling Rate: 1.0-3.0°C/s

Note: The recommended reflow profile is provided as a guideline. Optimal profile may differ due to oven type, assembly layout or other process variables.



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STORAGE & HANDLING:

- Refrigerate solder paste at 0-10°C. Shelf life is 6 months from production date (sealed package).
- Keep away from direct sunlight.
- Allow paste to reach ambient temperature (22-28°C) prior to use for 3-4 hrs. Do not heat up solder paste abruptly.
- Well mix paste with plastic spatula for 1min before use (jars packaging).
- It is recommended to finish fresh paste within 24 hrs. To maintain paste quality, make sure not to store used paste and fresh paste in the same jar.
- If printing process was interrupted for more than 1 hr, remove the remained paste from the stencil and seal in the jar.
- Recommended printing environment is 22-28°C and RH 30-60%.
- To clean up printed circuit boards, it is suggested to use ethanol or isopropanol

Note: For more information, please refer to solder paste application guideline sheet

HOW TO ORDER

SH63 – LXA – T4 – 500

Solder Alloy

SH63 = Sn63Pb37

Flux

LXA = ROLO

Particle Size

T3 = 20-45µm

T4 = 20-38µm

Weight / Packaging

30 = syringe 30g

100 = syringe 100g

150 = syringe 150g

250 = plastic jar 250g

500 = plastic jar 500g

600 = small cartridge 600g

1200 = large cartridge 1200g



CONTACTS

Tel.: +49-152-5106-5427


support@nevo-solder.com
www.nevo-solder.com


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